











LM237, LM337

SLVS047L-NOVEMBER 1981-REVISED JANUARY 2015

LMx37 3-Terminal Adjustable Regulators

Features

- Output Voltage Range Adjustable From -1.2 V to -37 V
- Output Current Capability of 1.5 A Max
- Input Regulation Typically 0.01% Per Input-Voltage Change
- Output Regulation Typically 0.3%
- Peak Output Current Constant Over Temperature Range of Regulator
- Ripple Rejection Typically 77 dB
- Direct Replacement for Industry-Standard LM237 and LM337

2 Applications

- Applications Requiring Negative Output Voltage or **Precision Current Regulation**
- Consumer Electronics
- **End Equipment**
- Portable Applications

3 Description

The LM237 and LM337 are adjustable 3-terminal negative-voltage regulators capable of supplying in excess of -1.5 A over an output voltage range of -1.2 V to -37 V. They require only two external resistors to set the output voltage and one output capacitor for frequency compensation.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|------------|--------------------|
| | TO-220 (4) | 10.16 mm x 8.82 mm |
| LMx37 | TO-263 (4) | 10.16 mm x 9.02 mm |
| | TO-252 (4) | 6.6 mm x 6.10 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Schematic

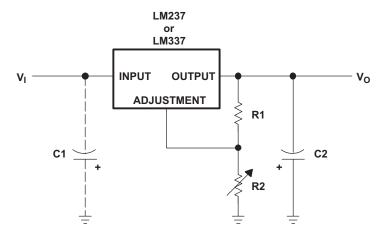




Table of Contents

| 2 Applications 1 8.4 Feature Description 8.5 Device Functional Modes 9 4 Simplified Schematic 1 9 Application and Implementation 9.1 Application Information 9.2 Typical Application 9.2 Typical Appli | ı | Features 1 | | 8.3 Design Schematic | 8 |
|--|---|--------------------------------|----|--------------------------------------|-----|
| 3 Description 1 8.5 Device Functional Modes | | Applications 1 | | 8.4 Feature Description | 8 |
| 4 Simplified Schematic 1 9 Application and Implementation 9.1 Application Information 9.2 Typical Application Information 9.2 Typical Application 9.2 | | | | 8.5 Device Functional Modes | 8 |
| 5Revision History29.1 Application Information6Pin Configuration and Functions39.2 Typical Application7Specifications410 Power Supply Recommendations7.1 Absolute Maximum Ratings411 Layout7.2 ESD Ratings411.1 Layout Guidelines7.3 Recommended Operating Conditions411.2 Layout Example7.4 Thermal Information412 Device and Documentation Support7.5 Electrical Characteristics512.1 Related Links7.6 Electrical Characteristics512.2 Trademarks7.7 Typical Characteristics512.3 Electrostatic Discharge Caution8 Detailed Description712.4 Glossary8.1 Overview7Mechanical, Packaging, and Orderable | | • | 9 | Application and Implementation | 9 |
| 6 Pin Configuration and Functions37 Specifications47.1 Absolute Maximum Ratings47.2 ESD Ratings47.3 Recommended Operating Conditions47.4 Thermal Information47.5 Electrical Characteristics57.6 Electrical Characteristics57.7 Typical Characteristics57.7 Typical Characteristics68 Detailed Description78.1 Overview7 | | | | 9.1 Application Information | 9 |
| 7 Specifications 4 10 Power Supply Recommendations 11 Layout 11.1 Layout Guidelines 11.1 Layout Example 11.2 Layout Example 11 | | | | 9.2 Typical Application | 9 |
| 7.1 Absolute Maximum Ratings 4 7.2 ESD Ratings 4 7.3 Recommended Operating Conditions 4 7.4 Thermal Information 4 7.5 Electrical Characteristics 5 7.6 Electrical Characteristics 5 7.7 Typical Characteristics 6 Detailed Description 7 8.1 Overview 7 11 Layout Guidelines 11.1 Layout Example 11.2 Layout Ex | | _ | 10 | Power Supply Recommendations | 10 |
| 7.2 ESD Ratings | | | | | |
| 7.3 Recommended Operating Conditions. 4 7.4 Thermal Information. 4 7.5 Electrical Characteristics. 5 7.6 Electrical Characteristics. 5 7.7 Typical Characteristics. 6 Detailed Description. 7 8.1 Overview. 7 11.2 Layout Example. 12 Device and Documentation Support. 12.1 Related Links. 12.2 Trademarks. 12.3 Electrostatic Discharge Caution. 12.4 Glossary. 12.4 Glossary. 13 Mechanical, Packaging, and Orderable Information. 14 11.2 Layout Example. 12.2 Device and Documentation Support. 12.1 Related Links. 12.2 Trademarks. 12.3 Electrostatic Discharge Caution. 12.4 Glossary. 12.4 Glossary. 12.4 Glossary. 13 Mechanical, Packaging, and Orderable Information. 14 12. Device and Documentation Support. 12.4 Glossary. 12.4 Glossary. 12.4 Glossary. 12.4 Glossary. 13 13. Overview. 14 14. Device and Documentation Support. 12.4 Glossary. 13 15. Device and Documentation Support. 14 16. Device and Documentation Support. 15 17. Typical Characteristics. 15 18. Detailed Description 17 19. Device and Documentation Support. 15 19. Dev | | • | | <u> </u> | |
| 7.4 Thermal Information 4 7.5 Electrical Characteristics 5 7.6 Electrical Characteristics 5 7.7 Typical Characteristics 6 8 Detailed Description 7 8.1 Overview 7 12 Device and Documentation Support 12.1 Related Links 12.2 Trademarks 12.2 Trademarks 12.3 Electrostatic Discharge Caution 12.4 Glossary 12.4 Glossary 13 Mechanical, Packaging, and Orderable Information | | • | | | |
| 7.5 Electrical Characteristics 5 12.1 Related Links 5 12.2 Trademarks 5 12.2 Trademarks 5 12.3 Electrostatic Discharge Caution 5 12.4 Glossary 5 12.5 Mechanical, Packaging, and Orderable 12.5 Information 5 12.6 Information 5 12.7 Information 5 12.8 Information 5 12.9 Information 5 Inform | | · | 12 | Device and Documentation Support | 11 |
| 7.6 Electrical Characteristics 5 12.2 Trademarks 5 12.3 Electrostatic Discharge Caution 5 12.4 Glossary 5 12.4 Glossary 7 13 Mechanical, Packaging, and Orderable Information | | | | | |
| 7.7 Typical Characteristics | | | | 12.2 Trademarks | 11 |
| 8 Detailed Description 7 12.4 Glossary 13 Mechanical, Packaging, and Orderable Information | | | | 12.3 Electrostatic Discharge Caution | 11 |
| 8.1 Overview | | •• | | 12.4 Glossary | 11 |
| O O Francisco de Picado | _ | • | 13 | | 4.4 |
| 8.2 Functional Block Diagram | | 8.2 Functional Block Diagram 7 | | information | 11 |

5 Revision History

Changes from Revision K (November 2007) to Revision L

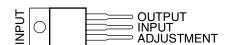
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Added Applications, Device Information table, Pin Functions table, ESD Ratings table, Thermal Information table, Typical Characteristics, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section.



6 Pin Configuration and Functions

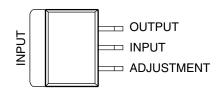




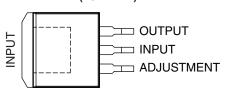
LM337...KCS (TO-220) PACKAGE (TOP VIEW)



LM337...KTE, KTP, OR KVU PACKAGE (TOP VIEW)



LM337...KTT (TO-263) PACKAGE (TOP VIEW)



Pin Functions

| PIN | | TYPE | DESCRIPTION |
|------------|-----|------|---|
| NAME | NO. | ITPE | DESCRIPTION |
| ADJUSTMENT | 1 | I | Adjustment pin for the output voltage. Connect two external resistors to adjust the output voltage. |
| INPUT | 2 | I | Input voltage. The input voltage and current will be designated V _I and I _I respectively. |
| OUTPUT | 3 | 0 | Output voltage. The output voltage and current will be designated $V_{\rm O}$ and $I_{\rm O}$ respectively. |



7 Specifications

7.1 Absolute Maximum Ratings

over operating temperature ranges (unless otherwise noted) (1)

| | | | MIN | MAX | UNIT |
|------------------|--|-------------------------------------|-----|-----|------|
| $V_I - V_O$ | Input-to-output differential voltage | | | -40 | V |
| T_{J} | Operating virtual junction temperature | | | 150 | °C |
| | Lead temperature | 1.6 mm (1/16 in) from case for 10 s | | 260 | °C |
| T _{stg} | Storage temperature range | | -65 | 150 | °C |

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 ESD Ratings

| | | | VALUE | UNIT |
|--------------------|-------------------------|---|-------|------|
| | | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins (1) | 1500 | |
| V _(ESD) | Electrostatic discharge | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins (2) | 1500 | V |

JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

Recommended Operating Conditions 7.3

| | | | MIN | MAX | UNIT |
|---------------|--|--|------|------|------|
| V_I - V_O | Input-to-output differential voltage | | -2.5 | -37 | |
| | $ V_1 - V_0 \le 40 \text{ V, P} \le 15 \text{ W}$ | | 10 | 1500 | ~ ^ |
| 10 | Output current | $ V_I - V_O \le 10 \text{ V, P} \le 15 \text{ W}$ | 6 | 1500 | mA |
| _ | | LM237 | -25 | 150 | ۰,0 |
| TJ | Operating virtual junction temperature | LM337 | 0 | 125 | °C |

7.4 Thermal Information

| | | LM237 | LM | x37 | | LM337 | | |
|---------------------|---|--------|--------|--------|--------|--------|--------|------|
| | THERMAL METRIC ⁽¹⁾ | КС | KCS | KTE | KTP | KTT | KVU | UNIT |
| | | 4 PINS | |
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance | 24.8 | 24.8 | 23 | 28 | 25.3 | 30.3 | |
| $R_{\theta JC(top}$ | Junction-to-case (top) thermal resistance | 3 | 3 | 3 | 19 | 30.3 | N/A | °C/W |

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report (SPRA953).



Electrical Characteristics

over recommended ranges of operating virtual junction temperature (unless otherwise noted)

| | | a.v.a/1) | | LM237 | | | LM337 | | LINUT | |
|--|--|-----------------------------|--------|--------|--------|--------|--------|--------|-------|--|
| PARAMETER | TEST CONDITI | ONS | MIN | TYP | MAX | MIN | TYP | MAX | UNIT | |
| I (2) | V V 0V/+- 40V/ | T _J = 25°C | | 0.01 | 0.02 | | 0.01 | 0.04 | %/V | |
| Input regulation (2) | $V_1 - V_0 = -3 \text{ V to } -40 \text{ V}$ | $T_J = MIN \text{ to } MAX$ | | 0.02 | 0.05 | | 0.02 | 0.07 | %/V | |
| Dinale rejection | V _O = -10 V, f = 120 Hz | | | 60 | | | 60 | | dB | |
| Ripple rejection | $V_{O} = -10 \text{ V}, f = 120 \text{ Hz}, C_{ADJ} = 0$ | 10 μF | 66 | 77 | | 66 | 77 | | uБ | |
| | I _O = 10 mA to 1.5 A, | V ₀ ≤ 5 V | | | 25 | | | 50 | mV | |
| Output regulation | $T_J = 25^{\circ}C$ | V _O ≥ 5 V | | 0.3% | 0.5% | | 0.3% | 1% | _ | |
| Output regulation | 10 50 40 45 4 | $ V_0 \le 5 \text{ V}$ | | | 50 | | | 70 | mV | |
| | $I_0 = 10 \text{ mA to } 1.5 \text{ A}$ | V _O ≥ 5 V | | | 1% | | | 1.5% | _ | |
| Output-voltage change with temperature | T _J = MIN to MAX | | 0.6% | | | 0.6% | | _ | | |
| Output-voltage long-term drift | After 1000 h at T _J = MAX and V _I | − V _O = −40 V | | 0.3% | 1% | | 0.3% | 1% | _ | |
| Output noise voltage | $f = 10 \text{ Hz to } 10 \text{ kHz}, T_J = 25^{\circ}\text{C}$ | | | 0.003% | | | 0.003% | | _ | |
| Minimum output current to | $ V_I - V_O \le 40 \text{ V}$ | | | 2.5 | 5 | | 2.5 | 10 | mA | |
| maintain regulation | $ V_I - V_O \le 10 \text{ V}$ | | | 1.2 | 3 | | 1.5 | 6 | ША | |
| Peak output current | $ V_I - V_O \le 15 \text{ V}$ | | 1.5 | 2.2 | | 1.5 | 2.2 | | Α | |
| reak output current | $ V_1 - V_0 \le 40 \text{ V}, T_J = 25^{\circ}\text{C}$ | | 0.24 | 0.4 | | 0.15 | 0.4 | | | |
| ADJUSTMENT current | | | 65 | 100 | | 65 | 100 | μΑ | | |
| Change in ADJUSTMENT current | $V_I - V_O = -2.5 \text{ V to } -40 \text{ V}, I_O = 10$ $T_J = 25^{\circ}\text{C}$ | | 2 | 5 | | 2 | 5 | μA | | |
| Reference voltage (OUTPUT | $V_I - V_O = -3 \text{ V to } -40 \text{ V},$ | T _J = 25°C | -1.225 | -1.25 | -1.275 | -1.213 | -1.25 | -1.287 | | |
| to ADJUSTMENT) | I _O = 10 mA to 1.5 A, P ≤ rated dissipation | T _J = MIN to MAX | -1.2 | -1.25 | -1.3 | -1.2 | -1.25 | -1.3 | V | |
| Thermal regulation | Initial T _J = 25°C, 10-ms pulse | | 0.002 | 0.02 | | 0.003 | 0.04 | %/W | | |

⁽¹⁾ Unless otherwise noted, the following test conditions apply: $|V_1 - V_0| = 5$ V and $I_0 = 0.5$ A. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. All characteristics are measured with a 0.1-µF capacitor across the input and a 1-µF capacitor across the output. Pulse-testing techniques are used to maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately.

(2) Input regulation is expressed here as the percentage change in output voltage per 1-V change at the input.

Electrical Characteristics

 $T_{.1} = 25^{\circ}C$

| DADAMETER | TEST CONDITIONS ⁽¹⁾ | LM | LM237, LM337 | | | |
|--|--|-------------------------|--------------|--------|--------|------|
| PARAMETER | TEST CONDITIONS. | MIN | TYP | MAX | UNIT | |
| Input regulation (2) | $V_1 - V_0 = -3 \text{ V to } -40 \text{ V}$ | | | 0.01 | 0.04 | %/V |
| Ripple rejection | $V_O = -10 \text{ V}, f = 120 \text{ Hz}$ | | | 60 | | dB |
| Rippie rejection | $V_{O} = -10 \text{ V}, f = 120 \text{ Hz}, C_{ADJ} = 10 \mu\text{F}$ | | 66 | 77 | | uБ |
| Output regulation | 1 10 m \ to 1 5 \ | $ V_0 \le 5 \text{ V}$ | | | 50 | mV |
| Output regulation | I _O = 10 mA to 1.5 A | $ V_O \ge 5 \text{ V}$ | | 0.3% | 1% | _ |
| Output noise voltage | f = 10 Hz to 10 kHz | | | 0.003% | | _ |
| Minimum output current to maintain | $ V_I - V_O \le 40 \text{ V}$ | | | 2.5 | 10 | mA |
| regulation | $ V_I - V_O \le 10 \text{ V}$ | | | 1.5 | 6 | IIIA |
| Dook output ourrent | $ V_I - V_O \le 15 \text{ V}$ | | 1.5 | 2.2 | | ۸ |
| Peak output current | $ V_I - V_O \le 40 \text{ V}$ | | 0.15 | 0.4 | | Α |
| ADJUSTMENT current | | | | 65 | 100 | μΑ |
| Change in ADJUSTMENT current | $V_I - V_O = -2.5 \text{ V to } -40 \text{ V}, I_O = 10 \text{ mA to}$ | MAX | | 2 | 5 | μΑ |
| Reference voltage (OUTPUT to ADJUSTMENT) | $V_I - V_O = -3 \text{ V to } -40 \text{ V}, I_O = 10 \text{ mA to } 0$ P \le \text{ rated dissipation} | I.5 A, | -1.213 | -1.25 | -1.287 | V |

Unless otherwise noted, the following test conditions apply: $|V_1 - V_0| = 5 \text{ V}$ and $I_0 = 0.5 \text{ A}$. All characteristics are measured with a 0.1μF capacitor across the input and a 1-μF capacitor across the output. Pulse-testing techniques are used to maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately.

Input regulation is expressed here as the percentage change in output voltage per 1-V change at the input.



7.7 Typical Characteristics

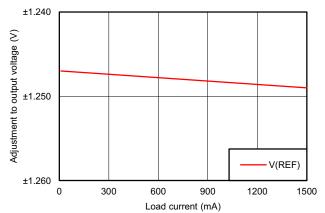


Figure 1. Adjustment Voltage vs Load current ($V_{IN} = -4.3 \text{ V}$)

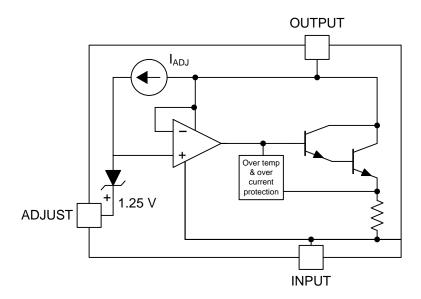


8 Detailed Description

8.1 Overview

The LMx37 devices are adjustable 3-terminal negative-voltage regulators capable of supplying in excess of -1.5 A over an output voltage range of -1.2 V to -37 V. They are exceptionally easy to use, requiring only two external resistors to set the output voltage and one output capacitor for frequency compensation. The current design is optimized for excellent regulation and low thermal transients. In addition, LM237 and LM337 feature internal current limiting, thermal shutdown, and safe-area compensation, making them virtually immune to failure by overloads. The LMx37 devices serve a wide variety of applications, including local on-card regulation, programmable output-voltage regulation, and precision current regulation.

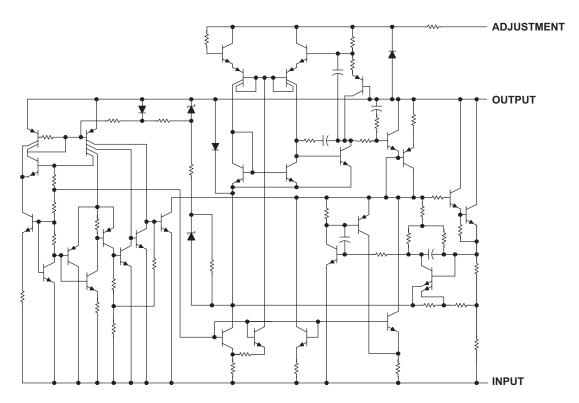
8.2 Functional Block Diagram



Submit Documentation Feedback



8.3 Design Schematic



8.4 Feature Description

8.4.1 Output Voltage Adjustment

The ADJUSTMENT pin serves as a voltage adjustment reference for the output. The ADJUSTMENT pin can be attached to a resistor divider circuit to adjust its own voltage level. The reference voltage $V_{ADJUSTMENT}$ will typically be 1.25 V higher than V_O .

8.5 Device Functional Modes

8.5.1 Adjustable Output Mode

The device has a single functional mode: Adjustable output voltage mode. A resistor divider circuit on the ADJUSTMENT pin determines the output voltage.

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9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

9.1.1 General Configurations

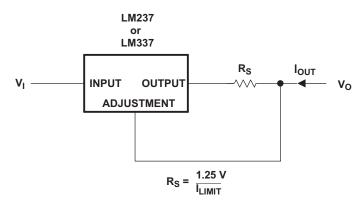


Figure 2. Current-Limiting Circuit

This application uses the LMx37 device's reference voltage, combined with the series resistor R_S , to limit the current to 1.25 V \div R_S

9.2 Typical Application

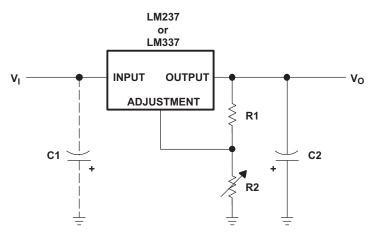


Figure 3. Adjustable Negative-Voltage Regulator

9.2.1 Design Requirements

- 1-μF solid tantalum on the input pin if the regulator is more than 10 cm from the power supply filter capacitor
- 1-μF solid tantalum or 10-μF aluminum electrolytic capacitor is required on the output pin for stability.
- R1, which is usually 120 Ω as part of the resistor divider.
- R2, which can be varied to change the value of V_O.



Typical Application (continued)

9.2.2 Detailed Design Procedure

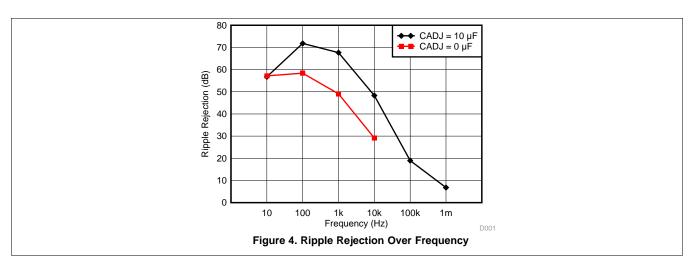
 V_O is determined by the values of R1 and R2. Choosing R1 = 120 Ω means that about 10.42 mA of current will flow through R1. The ~10 mA of current satisfies the minimum operating current and renders I_{REF} negligible. Since the current is coming from ground, the same amount of current will flow through R2. Therefore, the size of R2 will be the dominant factor in adjusting V_O . The relationship between R1, R2, and V_O is as follows:

$$R2=R1\left(\frac{V_{0}}{-1.25}-1\right)$$

where V_O is the output in volts.

(1)

9.2.3 Application Curves



10 Power Supply Recommendations

For best performance, the difference in voltage between the output and input must be between -2.5 V and -37 V. A 1- μ F solid tantalum capacitor is required on the input pin if the regulator is more than 10 cm from the power supply filter capacitor. A 1- μ F solid tantalum or 10- μ F aluminum electrolytic capacitor is required on the output pin for stability.

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11 Layout

11.1 Layout Guidelines

Traces on the input and output pins should be thick enough to carry 1.5 A of current without violating thermal requirements of the device or the system. In addition, a 1-μF solid tantalum capacitor is required on the input pin if the regulator is more than 10 cm from the power supply filter capacitor. A 1-μF solid tantalum or 10-μF aluminum electrolytic capacitor is required on the output pin for stability.

11.2 Layout Example

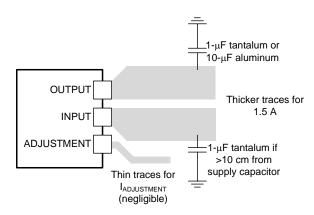


Figure 5. Layout Diagram

12 Device and Documentation Support

12.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 1. Related Links

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|-------|----------------|--------------|---------------------|---------------------|---------------------|
| LM237 | Click here | Click here | Click here | Click here | Click here |
| LM337 | Click here | Click here | Click here | Click here | Click here |

12.2 Trademarks

12.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.4 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package Drawing | | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------|------------------|--------------------|---|----------------|--------------|-------------------------------|---------------------|--------------|----------------------|---------|
| | | | | | | | (6) | | | | |
| LM237KCSE3 | LIFEBUY | TO-220 | KCS | 3 | 50 | RoHS & Green | SN | N / A for Pkg Type | -25 to 150 | LM237 | |
| LM337KCSE3 | LIFEBUY | TO-220 | KCS | 3 | 50 | RoHS & Green | SN | N / A for Pkg Type | 0 to 125 | LM337 | |
| LM337KTTR | LIFEBUY | DDPAK/ TO-263 | KTT | 3 | 500 | RoHS & Green | SN | Level-3-245C-168 HR | 0 to 125 | LM337 | |
| LM337KTTRG3 | LIFEBUY | DDPAK/ TO-263 | KTT | 3 | 500 | RoHS & Green | SN | Level-3-245C-168 HR | 0 to 125 | LM337 | |
| LM337KVURG3 | ACTIVE | TO-252 | KVU | 3 | 2500 | RoHS & Green | SN | Level-3-260C-168 HR | 0 to 125 | LM337 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and



PACKAGE OPTION ADDENDUM

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continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|---|
| В0 | Dimension designed to accommodate the component length |
| | Dimension designed to accommodate the component thickness |
| | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|------------------|--------------------|---|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| LM337KTTR | DDPAK/ TO-263 | KTT | 3 | 500 | 330.0 | 24.4 | 10.8 | 16.3 | 5.11 | 16.0 | 24.0 | Q2 |
| LM337KVURG3 | TO-252 | KVU | 3 | 2500 | 330.0 | 16.4 | 6.9 | 10.5 | 2.7 | 8.0 | 16.0 | Q2 |

www.ti.com 5-Jan-2022



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) | |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|--|
| LM337KTTR | DDPAK/TO-263 | KTT | 3 | 500 | 340.0 | 340.0 | 38.0 | |
| LM337KVURG3 | TO-252 | KVU | 3 | 2500 | 340.0 | 340.0 | 38.0 | |

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

TUBE



*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| LM237KCSE3 | KCS | TO-220 | 3 | 50 | 532 | 34.1 | 700 | 9.6 |
| LM337KCSE3 | KCS | TO-220 | 3 | 50 | 532 | 34.1 | 700 | 9.6 |



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4205521-2/E







NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. Shape may vary per different assembly sites.

 4. Reference JEDEC registration TO-252.





NOTES: (continued)

- 5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002(www.ti.com/lit/slm002) and SLMA004 (www.ti.com/lit/slma004).
- 6. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.





NOTES: (continued)



^{7.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations

design recommendations.

8. Board assembly site may have different recommendations for stencil design.

KTT (R-PSFM-G3)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- 3. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
- ⚠ Falls within JEDEC T0—263 variation AA, except minimum lead thickness and minimum exposed pad length.







NOTES:

- 1. Dimensions are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. Reference JEDEC registration TO-220.





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